

External_Type	Material_Group	Substances	CAS_Number	Mass	Mass_Percentage_in_Leaf	Massmg
Die		Silicon Carbide (SiC)	409-21-2	0.05	100.0	1.11
		Subtotal		0.05	100	1.11
Lead Frame	Copper alloy	Phosphorous (P)	7723-14-0	0.01	0.03	0.24
	Copper alloy	Nickel (Ni) - cas no. 7440-02-0	7440-02-0	0.01	0.03	0.24
	Copper alloy	Iron (Fe)	7439-89-6	0.03	0.1	0.81
	Copper alloy	Copper (Cu)	7440-50-8	33.92	99.84	807.71
		Subtotal		33.97	100	809
Mould Compound	Polymer	Phenol Formaldehyde resin (generic)	9003-35-4	5.21	8.0	124
	Polymer	Epichlorohydrin/Diethyleneglycol Epoxy resin (generic)	25928-94-3	6.51	10.0	155
	Filler	Silica fused	60676-86-0	52.07	80.0	1240
	Flame retardant	Metal hydroxide		1.3	2.0	31
		Subtotal		65.09	100	1550
Post-plating	Pure metal	Tin (Sn)	7440-31-5	0.67	100.0	16
		Subtotal		0.67	100	16
Wire	Pure metal	Aluminium (Al)	7429-90-5	0.09	100.0	2.16
	Pure metal	Aluminium (Al)	7429-90-5	0.06	100.0	1.43
		Subtotal		0.15	200	3.59
Die Attach	Lead alloy	Tin (Sn)	7440-31-5	0	2.0	0.03
	Lead alloy	Silver (Ag)	7440-22-4	0	2.5	0.04
	Lead alloy	Lead (Pb)	7439-92-1	0.06	95.5	1.52
		Subtotal		0.06	100	1.59
		Total		99.99	100	2381.29

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